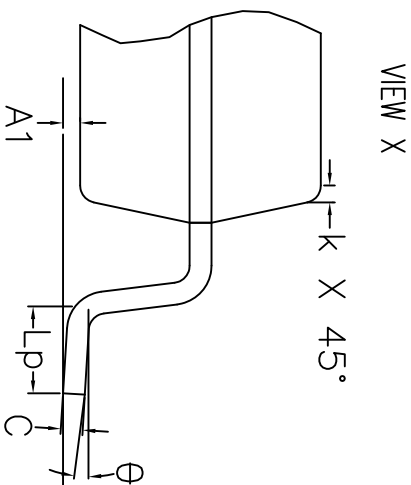
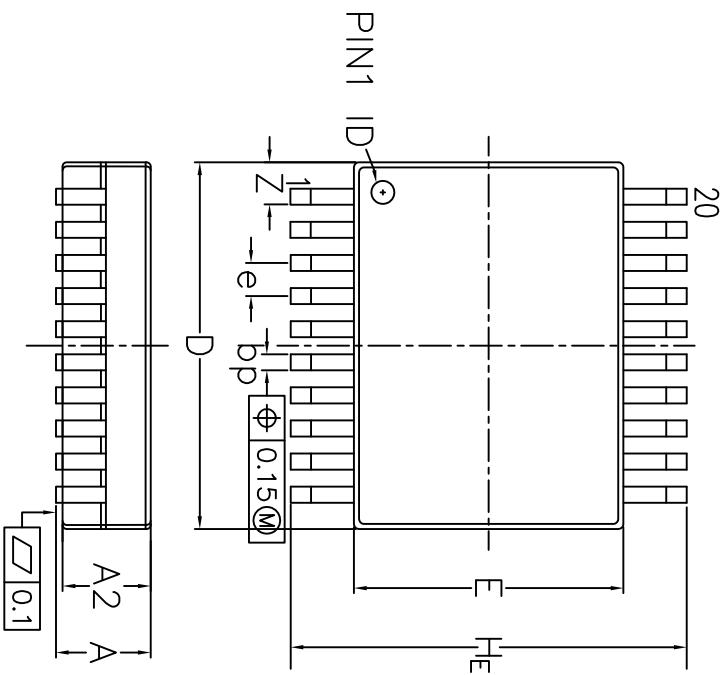


REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
00	INITIAL RELEASE	2/29/16	J.H




DIMENSIONS OF SUB-GROUP B1	
A max	1.99
bp min	0.25
bp max	0.38
e nom	0.65
He min	7.65
He max	7.90
Lpmin	0.63
Z max	0.74

DIMENSIONS OF SUB-GROUP C1	
A min	1.73
A1 min	0.05
A1 max	0.21
A2 min	1.68
A2 max	1.78
c min	0.09
c max	0.20
D min*	7.07
D max*	7.33
E min*	5.20
E max*	5.38
k min	0.25
θ max	0°
θ max	10°

* WITHOUT MOLD FLASH

1. WEIGHT ≤ 0.3 g
2. BODY MATERIAL LOW STRESS EPOXY
3. LEAD MATERIAL FeNi-ALLOY or Cu-ALLOY
4. LEAD FINISH SOLDER PLATING
5. LEAD FORM Z-BENDS
6. LEAD FORM Z-BENDS

TOLERANCES UNLESS SPECIFIED			
DECIMAL	±	8024 Silver Creek Valley Rd San Jose, CA 95138 PHONE: (408) 284-8200 FAX: (408) 284-3572	
ANGULAR	±	www.IDT.com	
APPROVALS	DATE	TITLE	SIZE
XXXX XXXX XXXX CHECKED	@AC3/29/16 DATE	PYG20 PACKAGE OUTLINE 5.3mm S50P	DRAWING No. PSC-4032-03
DO NOT SCALE DRAWING		SHEET	REV
		1 OF 1	00